

NanoSlic[®] Gold

NanoSlic[®] Gold stencils are the most advanced solder paste stencils available in the market today. Using advanced polymer chemistry, our coating has been developed to address the increasing demands confronting the electronics assembly industry. The coating is applied using a proprietary process which permanently coats both the underside of the stencil and aperture walls. This coating technology is highly hydrophobic and oleophobic which provides superior paste release. Some of the many benefits include:

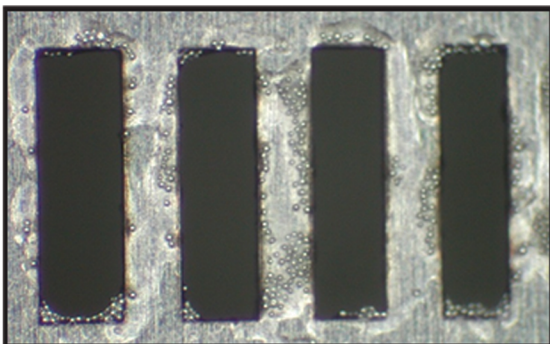
Increase in Paste Transfer Efficiency

Reduced Underside Cleaning

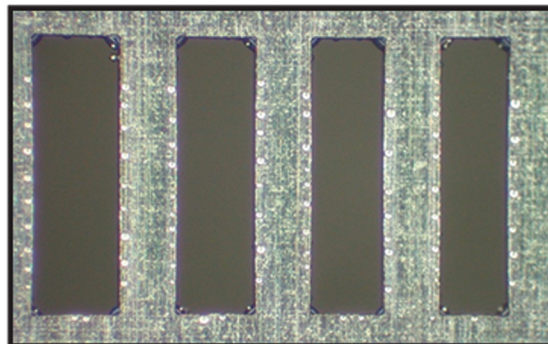
Consistent Print from Board to Board

Highly Robust and Durable Treatment

Uncoated Stencil



NanoSlic[®] Coated Stencil



Underside of stencils after 10 prints